ABSOLUTE MAXIMUM RATINGS

IN, SHDN, RESET to GND0.3V to +4.0V	(
OUT to GND0.3V to (V _{IN} + 0.3V)	
Output Short-Circuit DurationContinuous	,
Continuous Power Dissipation (TA = +70°C)	I
6-Pin Thin SOT23 (derate 9.1mW/°C above +70°C)727mW	
6-Pin TDFN (derate 24.4mW/°C above +70°C)1951mW	

Operating Temperature Range	40°C to +85°C
Junction Temperature	+150°C
Storage Temperature Range	65°C to +150°C
Lead Temperature (soldering, 10s)	+300°C

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

ELECTRICAL CHARACTERISTICS

 $(V_{IN} = (V_{OUT} + 0.5V)$ or 1.8V, whichever is greater; $\overline{SHDN} = IN$, $C_{IN} = 1\mu F$, $C_{OUT} = 4.7\mu F$, $T_A = -40^{\circ}C$ to +85°C, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$.) (Note 1)

PARAMETER	SYMBOL	CONDITIONS			TYP	MAX	UNITS
Input Voltage	VIN					3.60	V
Input Undervoltage Lockout	Vuvlo	V _{IN} rising (180mV typi	cal hysteresis)	1.30		1.60	V
		I _{OUT} = 150mA, T _A = +	-25°C	-0.5		+0.5	
Output Voltage Accuracy			$I_{OUT} = 1$ mA to 500mA, $V_{IN} = (V_{OUT} + 0.5V)$ to +3.6V			+1.5	%
Maximum Output Current	lout	Continuous		500			mA _{RMS}
Current Limit	ILIM	V _{OUT} = 96% of nomin	al value	550	850	1150	mA
		No load			70	140	
Ground Current	IQ	I _{OUT} = 500mA			90		μΑ
		Dropout (Note 2)			70		
Dropout Voltage	V _{IN} - V _{OUT}	I _{OUT} = 500mA, V _{OUT}	≥ 1.8V (Note 2)		175	350	mV
Load Regulation	ΔV_{LDR}	$I_{OUT} = 1$ mA to 500mA			0.02	0.5	%
Line Regulation	Δ VLNR	$V_{IN} = (V_{OUT} + 0.5V) to$	+3.6V, I _{OUT} = 100mA	-0.15	+0.01	+0.15	%/V
Output Noise		10Hz to 100kHz, I _{OUT} = 10mA			86		μV _{RMS}
PSRR		$f < 1kHz$, $I_{OUT} = 10mA$			70		dB
SHUTDOWN							
Chutdown Cupaly Current	lo	SHDN = GND	T _A = +25°C		0.001	1	
Shutdown Supply Current	loff	SHUN = GNU	T _A = +85°C		0.01		μA
CLIDN Input Logic Loyele	VIH	V _{IN} = 1.62V to 3.6V		1.4			V
SHDN Input Logic Levels	V _{IL}	$V_{IN} = 1.62V \text{ to } 3.6V$				0.6	V
SHDN Input Bias Current	1	V 0 0 V	$T_A = +25^{\circ}C$		1	300	nA
Show input bias current	ISHDN	$V_{\overline{SHDN}} = 0V \text{ or } 3.6V$	$T_A = +85^{\circ}C$		5		IIA
Turn-On Delay		From \overline{SHDN} high to OUT high, $V_{OUT} = 1.5V$			90		μs
RESET OUTPUT							
Reset Threshold Accuracy		V _{OUT} falling (1.7% typical hysteresis)			82.5	85	%Vout
RESET Output Low Voltage	Vol	IRESET = 100µA			1.5	100	mV
	V _{OL}	V _{IN} = +1.0V, I _{RESET} = 100μA			3	100	IIIV
		•		•			

ELECTRICAL CHARACTERISTICS (continued)

 $(V_{IN} = (V_{OUT} + 0.5V))$ or 1.8V, whichever is greater; $\overline{SHDN} = IN$, $C_{IN} = 1\mu F$, $C_{OUT} = 4.7\mu F$, $T_A = -40^{\circ}C$ to +85°C, unless otherwise noted. Typical values are at $T_A = +25^{\circ}C$.) (Note 1)

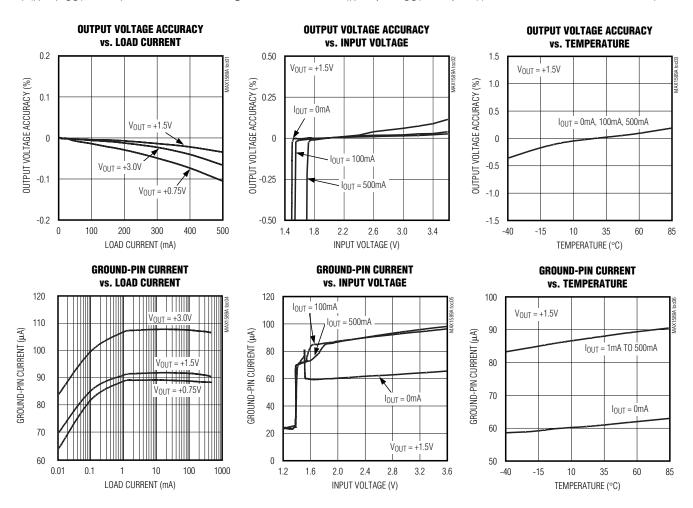
PARAMETER	SYMBOL	CONDITIONS			TYP	MAX	UNITS
RESET Output High	lou	$V_{\overline{RESET}} = 3.6V,$	T _A = +25°C		0.001	1	μA
Leakage Current	Іон	RESET not asserted	T _A = +85°C		0.01		μА
Reset Delay	t _{RP}	From V _{OUT} high to RESET rising			100	160	ms
THERMAL PROTECTION							
Thermal-Shutdown Temperature	TSHDN				+165		°C
Thermal-Shutdown Hysteresis	∆T _{SHDN}				15		°C

Note 1: Limits are 100% production tested at $T_A = +25$ °C. Limits over the operating temperature range are guaranteed by design.

Note 2: The dropout voltage is defined as V_{IN} - V_{OUT} , when V_{OUT} is 4% lower than the value of V_{OUT} when $V_{IN} = V_{OUT} + 0.5V$.

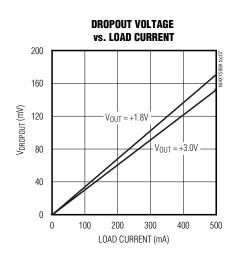
Typical Operating Characteristics

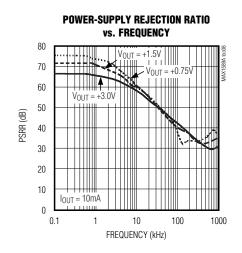
 $(V_{IN} = (V_{OUT} + 0.5V) \text{ or } 1.8V, \text{ whichever is greater; } \overline{SHDN} = IN, C_{IN} = 1\mu\text{F}, C_{OUT} = 4.7\mu\text{F}, T_A = +25^{\circ}\text{C}, \text{ unless otherwise noted.})$

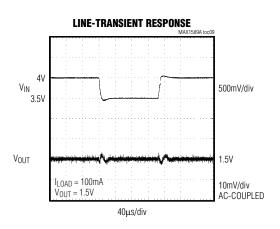


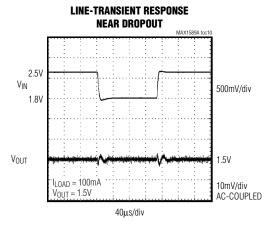
Typical Operating Characteristics (continued)

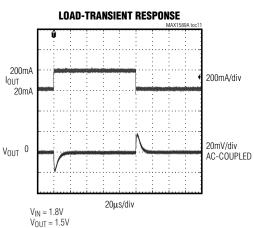
 $(V_{IN} = (V_{OUT} + 0.5V))$ or 1.8V, whichever is greater; $\overline{SHDN} = IN$, $C_{IN} = 1\mu F$, $C_{OUT} = 4.7\mu F$, $T_{A} = +25^{\circ}C$, unless otherwise noted.)

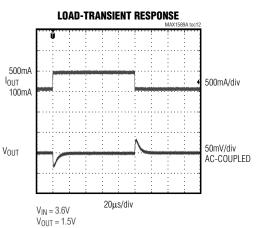






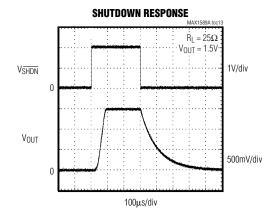


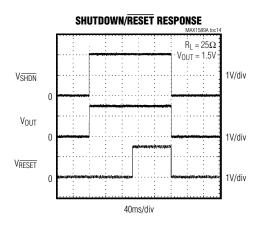


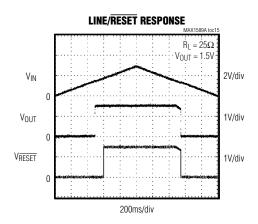


Typical Operating Characteristics (continued)

 $(V_{IN} = (V_{OUT} + 0.5V) \text{ or } 1.8V, \text{ whichever is greater; } \overline{SHDN} = IN, C_{IN} = 1\mu\text{F}, C_{OUT} = 4.7\mu\text{F}, T_{A} = +25^{\circ}\text{C}, \text{ unless otherwise noted.})$







Pin Description

PIN		NAME	FUNCTION				
SOT23	TDFN	INAIVIE	FUNCTION				
1	6	IN	Regulator Input. Supply voltage can range from +1.62V to +3.6V. Bypass IN with at least a 1µF ceramic capacitor to GND (see the <i>Capacitor Selection and Regulator Stability</i> section).				
2	_	GND	Ground. GND also functions as a heatsink. Solder GND to a large pad or circuit-board ground plane to maximize SOT23 power dissipation.				
_	4	GND	Ground				
3	5	SHDN	Active-Low Shutdown Input. A logic-low reduces supply current to below 1µA. Connect to IN or logic-high for normal operation.				
4	3	RESET	Active-Low, Open-Drain Reset Output. RESET rises 100ms after the output has achieved regulation. RESET falls immediately if V _{OUT} drops below 82.5% of its nominal voltage, or if the MAX1589A is shut down.				
5	2	I.C.	Internally Connected. Leave floating or connect to GND.				
6	1	OUT	Regulator Output. Sources up to 500mA. Bypass with a 4.7µF low-ESR ceramic capacitor to GND.				
_	Exposed Pad	EP	Ground. EP also functions as a heatsink. Solder EP to a large pad or circuit-board ground plane to maximize TDFN power dissipation.				

Detailed Description

The MAX1589A is a low-dropout, low-quiescent-current, high-accuracy linear regulator designed primarily for battery-powered applications. The device supplies loads up to 500mA and is available with preset output voltages from +0.75V to +3.0V. As illustrated in Figure 1, the MAX1589A contains a reference, an error amplifier, a p-channel pass transistor, an internal feedback voltage-divider, and a power-good comparator.

The error amplifier compares the reference with the feedback voltage and amplifies the difference. If the feedback voltage is lower than the reference voltage, the pass-transistor gate is pulled lower, allowing more current to pass to the output and increasing the output voltage. If the feedback voltage is too high, the pass-transistor gate is pulled up, allowing less current to pass to the output.

Internal p-Channel Pass Transistor

The MAX1589A features a 0.33 Ω (RDS(ON)) p-channel MOSFET pass transistor. Unlike similar designs using pnp pass transistors, p-channel MOSFETs require no base drive, which reduces quiescent current. pnp-based regulators also waste considerable current in dropout when the pass transistor saturates and use high base-drive currents under large loads. The

MAX1589A does not suffer from these problems and consumes only 90µA (typ) of quiescent current under heavy loads, as well as in dropout.

Shutdown

Pull \overline{SHDN} low to enter shutdown. During shutdown, the output is disconnected from the input, an internal 1.5k Ω resistor pulls OUT to GND, \overline{RESET} is actively pulled low, and supply current drops below 1 μ A.

RESET Output

The MAX1589A's microprocessor (µP) supervisory circuitry asserts a guaranteed logic-low reset during power-up, power-down, and brownout conditions down to +1V. RESET asserts when VOUT is below the reset threshold and remains asserted for at least 70ms (tRP) after VOUT rises above the reset threshold.

Current Limit

The MAX1589A monitors and controls the pass transistor's gate voltage, limiting the output current to 850mA (typ). If the output current exceeds I_{LIM} , the MAX1589A output voltage drops.

Thermal-Overload Protection

Thermal-overload protection limits total power dissipation in the MAX1589A. When the junction temperature exceeds +165°C, a thermal sensor turns off the pass

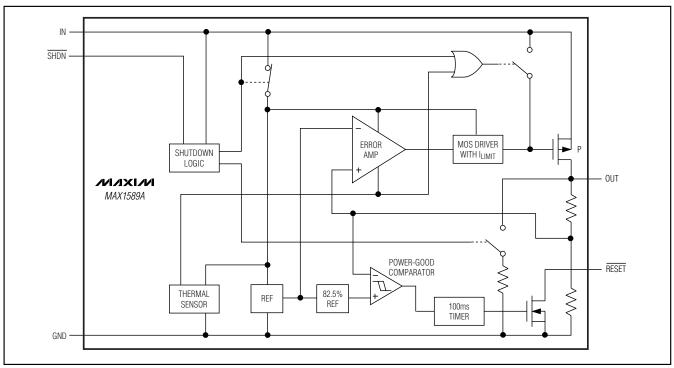


Figure 1. Functional Diagram

transistor, allowing the IC to cool. The thermal sensor turns the pass transistor on again after the junction temperature cools by 15°C, resulting in a pulsed output during continuous thermal-overload conditions. Thermal-overload protection safeguards the MAX1589A in the event of fault conditions. For continuous operation, do not exceed the absolute maximum junction-temperature rating of +150°C.

Operating Region and Power Dissipation

The MAX1589A's maximum power dissipation depends on the thermal resistance of the IC package and circuit board, the temperature difference between the die junction and ambient air, and the rate of airflow. The power dissipated in the device is $P = I_{OUT} \times (V_{IN} - V_{OUT})$. The maximum allowed power dissipation is:

$$P_{MAX} = (T_{J(MAX)} - T_{A}) / (\theta_{JC} + \theta_{CA})$$

where $T_{J(MAX)}$ - T_{A} is the temperature difference between the MAX1589A die junction and the surrounding air, θ_{JC} is the thermal resistance of the junction to the case, and θ_{CA} is the thermal resistance from the case through the PC board, copper traces, and other materials to the surrounding air. Typical thermal resistance ($\theta_{JC} + \theta_{JA}$) for a device mounted to a 1in square, 1oz copper pad is

41°C/W for the 3mm x 3mm TDFN package, and 110°C/W for the 6-pin thin SOT23 package. For best heatsinking, expand the copper connected to GND, or the exposed paddle.

The MAX1589A delivers up to 500mA and operates with an input voltage up to +3.6V. However, when using the 6-pin SOT23 version, high output currents can only be sustained when the input-output differential voltage is low, as shown in Figure 2.

The maximum allowed power dissipation for the 6-pin TDFN is 1.951W at $T_A = +70^{\circ}$ C. Figure 3 shows that the maximum input-output differential voltage is not limited by the TDFN package power rating.

Applications Information

Capacitor Selection and Regulator Stability

Capacitors are required at the MAX1589A's input and output for stable operation over the full temperature range and with load currents up to 500mA. Connect a 1µF ceramic capacitor between IN and GND and a 4.7µF low-ESR ceramic capacitor between OUT and GND. The input capacitor (CIN) lowers the source impedance of the input supply. Use larger output

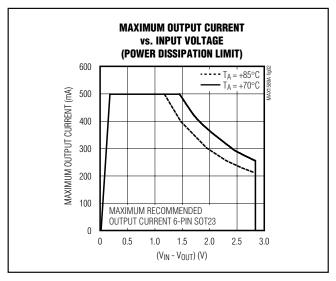


Figure 2. Power Operating Regions for 6-Pin SOT23: Maximum Output Current vs. Input Voltage

capacitors to reduce noise and improve load-transient response, stability, and power-supply rejection.

The output capacitor's equivalent series resistance (ESR) affects stability and output noise. Use output capacitors with an ESR of $30 m\Omega$ or less to ensure stability and optimize transient response. Surface-mount ceramic capacitors have very low ESR and are commonly available in values up to $10 \mu F$. Connect C_{IN} and C_{OUT} as close to the MAX1589A as possible to minimize the impact of PC board trace inductance.

Noise, PSRR, and Transient Response

The MAX1589A is designed to operate with low dropout voltages and low quiescent currents in battery-powered systems, while still maintaining good noise, transient response, and AC rejection. See the *Typical Operating Characteristics* for a plot of Power-Supply Rejection Ratio (PSRR) vs. Frequency. When operating from noisy sources, improved supply-noise rejection and transient response can be achieved by increasing the values of the input and output bypass capacitors and through passive filtering techniques.

The MAX1589A load-transient response (see the *Typical Operating Characteristics*) shows two compo-

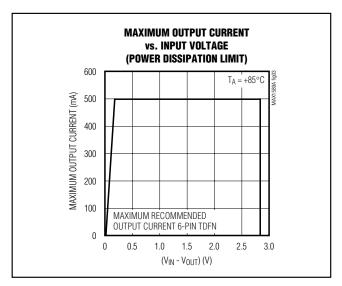


Figure 3. Power Operating Region for 6-Pin TDFN: Maximum Output Current vs. Input Voltage

nents of the output response: a near-zero DC shift from the output impedance due to the load-current change, and the transient response. A typical transient response for a step change in the load current from 100mA to 500mA is 35mV. Increasing the output capacitor's value and decreasing the ESR attenuates the overshoot.

Input-Output (Dropout) Voltage

A regulator's minimum input-output voltage difference (dropout voltage) determines the lowest usable supply voltage. In battery-powered systems, this determines the useful end-of-life battery voltage. Because the MAX1589A uses a p-channel MOSFET pass transistor, its dropout voltage is a function of drain-to-source on-resistance (RDS(ON) = 0.33Ω) multiplied by the load current (see the *Typical Operating Characteristics*):

$$V_{DROPOUT} = V_{IN} - V_{OUT} = 0.33\Omega \times I_{OUT}$$

The MAX1589A ground current reduces to $70\mu A$ in dropout.

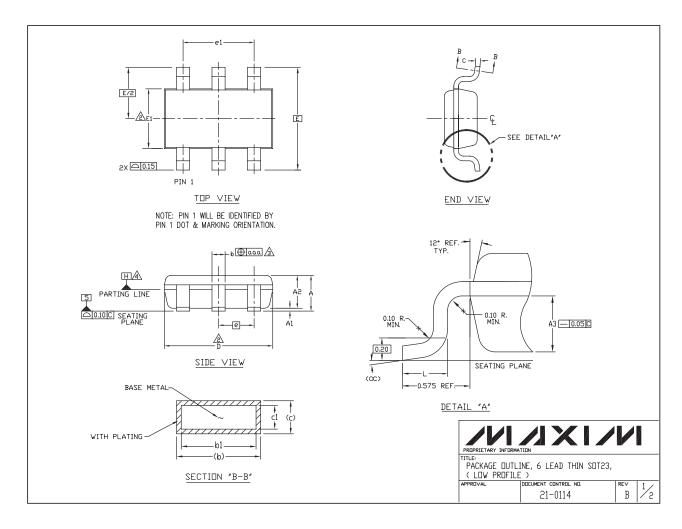
_ Chip Information

TRANSISTOR COUNT: 2556

PROCESS: BiCMOS

Package Information

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)



Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.

"D" AND "E1" ARE REFERENCE DATUM AND DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS, AND ARE MEASURED AT THE BOTTOM PARTING LINE. MOLD FLASH OR PROTRUSION SHALL NOT EXCEED 0.15mm ON "D" AND 0.25mm ON "E" PER SIDE.

THE LEAD WIDTH DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.07mm TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION.

DATUM PLANE "H" LOCATED AT MOLD PARTING LINE AND COINCIDENT WITH LEAD, WHERE LEAD EXITS PLASTIC BODY AT THE BOTTOM OF PARTING LINE.

THE LEAD TIPS MUST LINE WITHIN A SPECIFIED TOLERANCE ZONE. THIS TOLERANCE ZONE IS DEFINED BY TWO PARALLEL LINES. ONE PLANE IS THE SEATING PLANE, DATUM [-C-]; AND THE OTHER PLANE IS AT THE SPECIFIED DISTANCE FROM [-C-] IN THE DIRECTION INDICATED. FORMED LEADS SHALL BE PLANAR WITH RESPECT TO ONE ANOTHER WITH 0.10mm AT SEATING PLANE.

6. THIS PART IS COMPLIANT WITH JEDEC SPECIFICATION
MO-193 EXCEPT FOR THE "e" DIMENSION WHICH IS 0.95mm
INSTEAD OF 1.00mm. THIS PART IS IN FULL COMPLIANCE TO
EIAJ SPECIFICATION SC-74.

SYMBOLS						
	MIN	NDM	MAX			
Α	-	-	1.10			
A1	0.05	0.075	0.10			
A2	0.85	0.88	0.90			
A3		0.50 BSC				
b	0.30	-	0.45			
b1	0.25	0.35	0.40			
С	0.15	-	0.20			
⊂1	0.12	0.127	0.15			
D	2.80	2.90	3.00			
E		2.75 BSC				
E1	1.55	1.60	1.65			
L	0.30	0.40	0.50			
e1	1.90 BSC					
е	0.95 BSC					
∞	0-	4-	8-			
ممم	0.20					



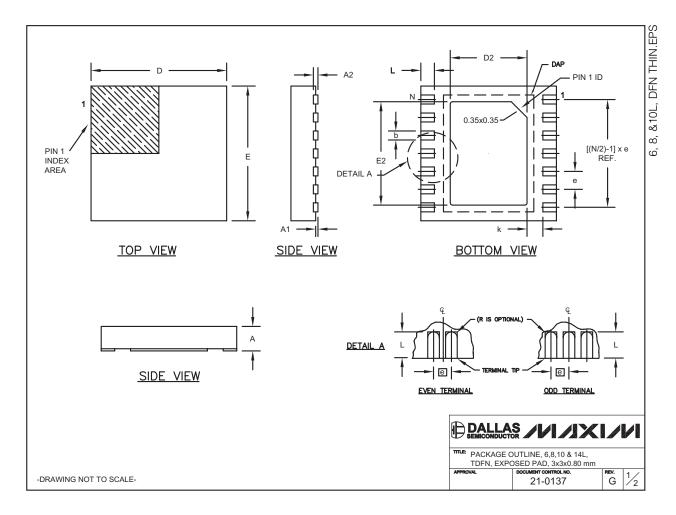
PACKAGE DUTLINE, 6 LEAD THIN SDT23, (LOW PROFILE)

PROVAL DOCUMENT CONTROL NO. 21-0114

B 2

Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages.)



Package Information (continued)

(The package drawing(s) in this data sheet may not reflect the most current specifications. For the latest package outline information, go to www.maxim-ic.com/packages)

COMMON DIMENSIONS						
SYMBOL	MIN.	MAX.				
Α	0.70	0.80				
D	2.90	3.10				
E	2.90	3.10				
A1	0.00	0.05				
L	0.20	0.40				
k	k 0.25 MIN.					
A2	0.20 REF.					

PACKAGE VARIATIONS								
PKG. CODE	N	D2	E2	е	JEDEC SPEC	b	[(N/2)-1] x e	DOWNBONDS ALLOWED
T633-1	6	1.50-0.10	2.30-0.10	0.95 BSC	MO229 / WEEA	0.40-0.05	1.90 REF	NO
T633-2	6	1.50-0.10	2.30-0.10	0.95 BSC	MO229 / WEEA	0.40-0.05	1.90 REF	NO
T833-1	8	1.50-0.10	2.30-0.10	0.65 BSC	MO229 / WEEC	0.30-0.05	1.95 REF	NO
T833-2	8	1.50-0.10	2.30-0.10	0.65 BSC	MO229 / WEEC	0.30-0.05	1.95 REF	NO
T833-3	8	1.50-0.10	2.30-0.10	0.65 BSC	MO229 / WEEC	0.30-0.05	1.95 REF	YES
T1033-1	10	1.50-0.10	2.30-0.10	0.50 BSC	MO229 / WEED-3	0.25-0.05	2.00 REF	NO
T1433-1	14	1.70-0.10	2.30-0.10	0.40 BSC		0.20-0.05	2.40 REF	YES
T1433-2	14	1.70-0.10	2.30-0.10	0.40 BSC		0.20-0.05	2.40 REF	NO

- NOTES:
 1. ALL DIMENSIONS ARE IN mm. ANGLES IN DEGREES.
 2. COPLANARITY SHALL NOT EXCEED 0.08 mm.
 3. WARPAGE SHALL NOT EXCEED 0.10 mm.

- 4. PACKAGE LENGTH/PACKAGE WIDTH ARE CONSIDERED AS SPECIAL CHARACTERISTIC(S).
- 5. DRAWING CONFORMS TO JEDEC MO229, EXCEPT DIMENSIONS "D2" AND "E2", AND T1433-1 & T1433-2.
- 6. "N" IS THE TOTAL NUMBER OF LEADS.
 7. NUMBER OF LEADS SHOWN ARE FOR REFERENCE ONLY.

DALLAS / I / IX / I PACKAGE OUTLINE, 6,8,10 & 14L. TDFN, EXPOSED PAD, 3x3x0.80 mm 21-0137 G

-DRAWING NOT TO SCALE-

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